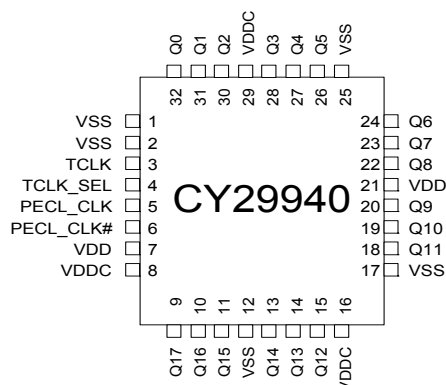


Pin Configuration



Pin Description

Pin	Name	PWR	I/O ^[1]	Description
5	PECL_CLK		I, PU	PECL input clock
6	PECL_CLK#		I, PD	PECL input clock
3	TCLK		I, PD	External reference/test clock input
9, 10, 11, 13, 14, 15, 18, 19, 20, 22, 23, 24, 26, 27, 28, 30, 31, 32	Q(17:0)	VDDC	O	Clock outputs
4	TCLK_SEL		I, PD	Clock Select Input. When LOW, PECL clock is selected and when HIGH TCLK is selected.
8, 16, 29	VDDC			3.3 V or 2.5 V power supply for output clock buffers
7, 21	VDD			3.3 V or 2.5 V power supply
1, 2, 12, 17, 25	VSS			Common ground

Note

1. PD = Internal Pull-Down, PU = Internal Pull-up

Maximum Ratings

Exceeding the maximum ratings^[2] may impair the useful life of the device. User guidelines are not tested.

Maximum input voltage relative to V_{SS} $V_{SS} - 0.3\text{ V}$

Maximum input voltage relative to V_{DD} $V_{DD} + 0.3\text{ V}$

Storage temperature -65 °C to $+150\text{ °C}$

Operating temperature -40 °C to $+85\text{ °C}$

Maximum ESD protection 2 kV

Maximum power supply 5.5 V

Maximum input current $\pm 20\text{ mA}$

This device contains circuitry to protect the inputs against damage due to high static voltages or electric field; however, precautions should be taken to avoid application of any voltage higher than the maximum rated voltages to this circuit. For proper operation, V_{in} and V_{out} should be constrained to the range:

$$V_{SS} < (V_{in} \text{ or } V_{out}) < V_{DD}$$

Unused inputs must always be tied to an appropriate logic voltage level (either V_{SS} or V_{DD}).

DC Parameters

$V_{DD} = 3.3\text{ V} \pm 5\%$ or $2.5\text{ V} \pm 5\%$, $V_{DDC} = 3.3\text{ V} \pm 5\%$ or $2.5\text{ V} \pm 5\%$, $T_A = -40\text{ °C}$ to $+85\text{ °C}$

Parameter ^[2]	Description	Conditions	Min	Typ	Max	Unit
V_{IL}	Input low voltage		V_{SS}	–	0.8	V
V_{IH}	Input high voltage		2.0	–	V_{DD}	V
I_{IL}	Input low current ^[3]		–	–	–200	μA
I_{IH}	Input high current ^[3]		–	–	200	μA
V_{PP}	Peak-to-peak input voltage PECL_CLK		500	–	1000	mV
V_{CMR}	Common mode range ^[4] PECL_CLK	$V_{DD} = 3.3\text{ V}$	$V_{DD} - 1.4$	–	$V_{DD} - 0.6$	V
		$V_{DD} = 2.5\text{ V}$	$V_{DD} - 1.0$	–	$V_{DD} - 0.6$	V
V_{OL}	Output low voltage ^[5, 6, 7]	$I_{OL} = 20\text{ mA}$	–	–	0.5	V
V_{OH}	Output high voltage ^[5, 6, 7]	$I_{OH} = -20\text{ mA}$, $V_{DDC} = 3.3\text{ V}$	2.4	–	–	V
		$I_{OH} = -20\text{ mA}$, $V_{DDC} = 2.5\text{ V}$	1.8	–	–	V
I_{DDQ}	Quiescent supply current		–	5	7	mA
I_{DD}	Dynamic supply current	$V_{DD} = 3.3\text{ V}$, Outputs at 150 MHz, $C_L = 15\text{ pF}$	–	285	–	mA
		$V_{DD} = 3.3\text{ V}$, Outputs at 200 MHz, $C_L = 15\text{ pF}$	–	335	–	
		$V_{DD} = 2.5\text{ V}$, Outputs at 150 MHz, $C_L = 15\text{ pF}$	–	200	–	
		$V_{DD} = 2.5\text{ V}$, Outputs at 200 MHz, $C_L = 15\text{ pF}$	–	240	–	
Z_{out}	Output impedance	$V_{DD} = 3.3\text{ V}$	8	12	16	Ω
		$V_{DD} = 2.5\text{ V}$	10	15	20	
C_{in}	Input capacitance		–	4	–	pF

Thermal Resistance

Parameter ^[8]	Description	Test Conditions	32-pin TQFP	Unit
θ_{JA}	Thermal resistance (junction to ambient)	Test conditions follow standard test methods and procedures for measuring thermal impedance, in accordance with EIA/JESD51.	67	$^{\circ}\text{C/W}$
θ_{JC}	Thermal resistance (junction to case)		28	$^{\circ}\text{C/W}$

Notes

- Multiple Supplies:** The Voltage on any input or I/O pin cannot exceed the power pin during power-up. Power supply sequencing is not required.
- Inputs have pull-up/pull-down resistors that effect input current.
- The VCMR is the difference from the most positive side of the differential input signal. Normal operation is obtained when the "High" input is within the VCMR range and the input lies within the VPP specification. Driving series or parallel terminated 50 Ω (or 50 Ω to $V_{DD}/2$) transmission lines
- Outputs driving 50 Ω transmission lines.
- See Figure 1 on page 5 and Figure 2 on page 5.
- 50% input duty cycle.
- These parameters are guaranteed by design and are not tested.

AC Parameters^[9]

$V_{DD} = 3.3 \text{ V} \pm 5\%$ or $2.5 \text{ V} \pm 5\%$, $V_{DDC} = 3.3 \text{ V} \pm 5\%$ or $2.5 \text{ V} \pm 5\%$, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$

Parameter	Description	Conditions		Min	Typ	Max	Unit
F _{max}	Input frequency		—	—	—	200	MHz
t _{PD}	PECL_CLK to Q Delay ^[10, 11, 12] ≤ 150 MHz	V _{DD} = 3.3 V, 85 °C	t _{PHL}	2.0	—	3.2	ns
			t _{PLH}	2.1	—	3.4	
		V _{DD} = 3.3 V, 70 °C	t _{PHL}	1.9	—	3.1	
			t _{PLH}	2.0	—	3.2	
		V _{DD} = 2.5 V, 85 °C	t _{PHL}	2.5	—	5.2	
			t _{PLH}	2.6	—	5	
		V _{DD} = 2.5 V, 70 °C	t _{PHL}	2.5	—	5	
			t _{PLH}	2.6	—	5	
t _{PD}	LVCMOS to Q Delay ^[10, 11, 12] ≤ 150 MHz	V _{DD} = 3.3 V, 85 °C	t _{PHL}	1.9	—	3	ns
			t _{PLH}	2.0	—	3.2	
		V _{DD} = 3.3 V, 70 °C	t _{PHL}	1.8	—	2.9	
			t _{PLH}	1.8	—	3.1	
		V _{DD} = 2.5 V, 85 °C	t _{PHL}	2.5	—	4	
			t _{PLH}	2.5	—	4	
		V _{DD} = 2.5 V, 70 °C	t _{PHL}	2.3	—	3.8	
			t _{PLH}	2.3	—	3.8	
t _J	Total jitter	V _{DD} = 3.3 V @ 150 MHz		—	—	10	ps
F _{outDC}	Output duty cycle ^[10, 11, 13]	FCLK < 134 MHz		—	—	55	%
		FCLK > 134 MHz		—	—	60	
T _{skew}	Output-to-output skew ^[10, 11]	V _{DD} = 3.3 V		—	60	150	ps
		V _{DD} = 2.5 V		—	—	200	
T _{skew} (pp)	Part-to-part skew ^[14]	PECL, V _{DDC} = 3.3 V		—	—	1.4	ns
		PECL, V _{DDC} = 2.5 V		—	—	2.2	
T _{skew} (pp)	Part-to-part skew ^[14]	TCLK, V _{DDC} = 3.3 V		—	—	1.2	ns
		TCLK, V _{DDC} = 2.5 V		—	—	1.7	
T _{skew} (pp)	Part-to-part skew ^[15]	PECL_CLK		—	—	850	ps
		TCLK		—	—	750	
t _R /t _F	Output clocks rise/fall time ^[10, 11]	0.7 V to 2.0 V, V _{DDC} = 3.3 V		0.3	—	1.1	ns
		0.5 V to 1.8 V, V _{DDC} = 2.5 V		0.3	—	1.2	

Notes

9. Parameters are guaranteed by design and characterization. Not 100% tested in production. All parameters specified with loaded outputs.

10. Outputs driving 50Ω transmission lines.

11. See Figure 1 on page 5 and Figure 2 on page 5.

12. Parameters tested @ 150 MHz.

13. 50% input duty cycle.

14. Across temperature and voltage ranges, includes output skew.

15. For a specific temperature and voltage, includes output skew.

Figure 1. LVCMOS_CLK CY29940 Test Reference for $V_{CC} = 3.3\text{ V}$ and $V_{CC} = 2.5\text{ V}$

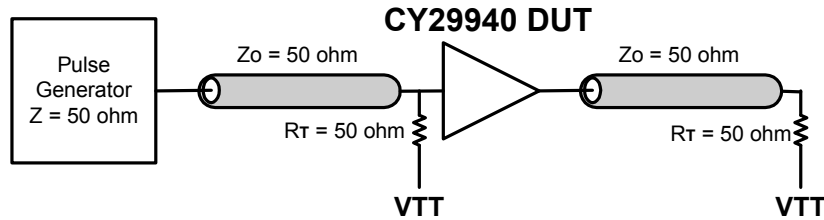


Figure 2. PECL_CLK CY29940 Test Reference for $V_{CC} = 3.3\text{ V}$ and $V_{CC} = 2.5\text{ V}$

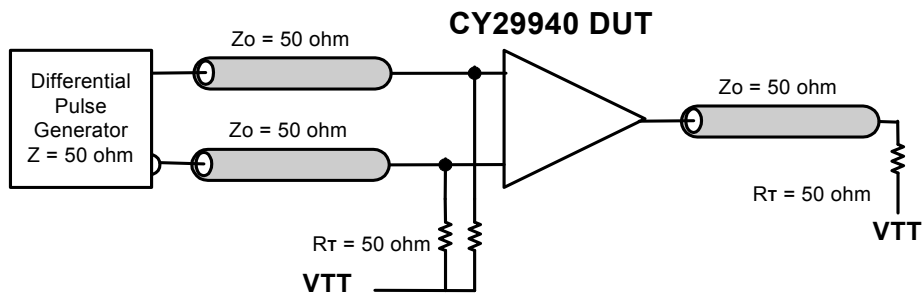


Figure 3. Propagation Delay (TPD) Test Reference

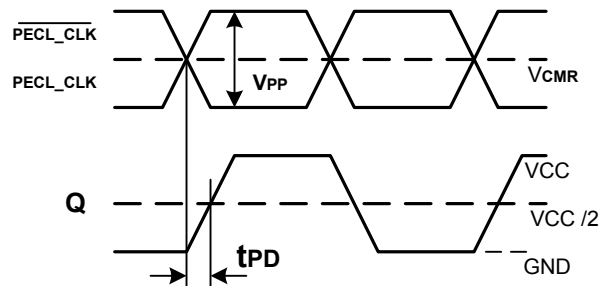


Figure 4. LVCMOS Propagation Delay (TPD) Test Reference

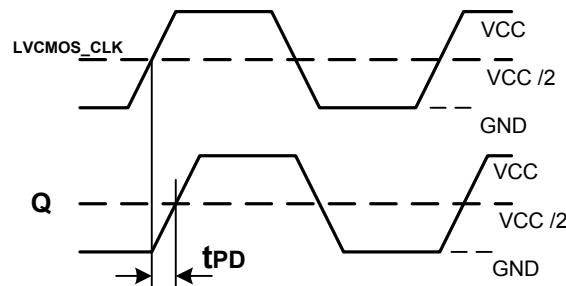
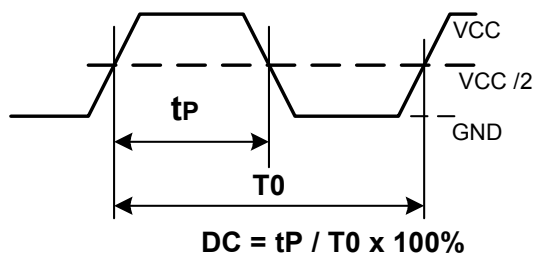
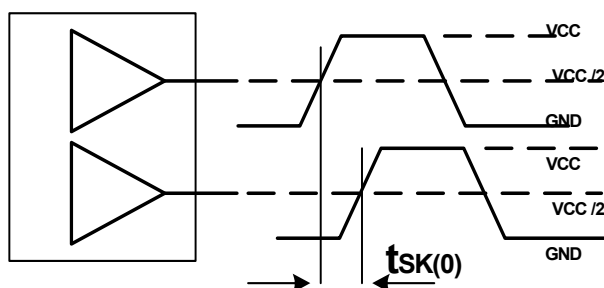
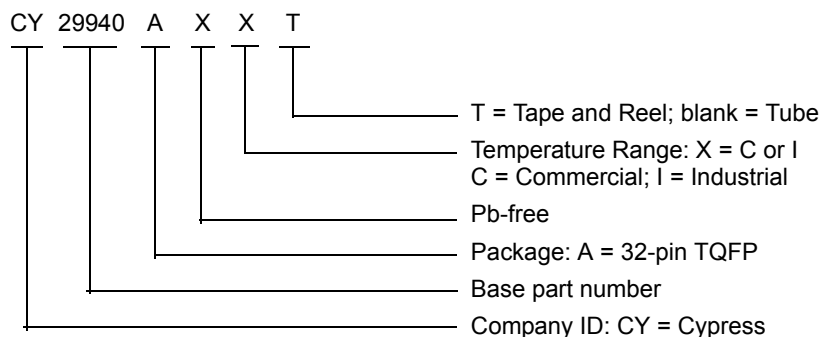


Figure 5. Output Duty Cycle (FoutDC)

Figure 6. Output-to-Output Skew tsk(0)


Ordering Information

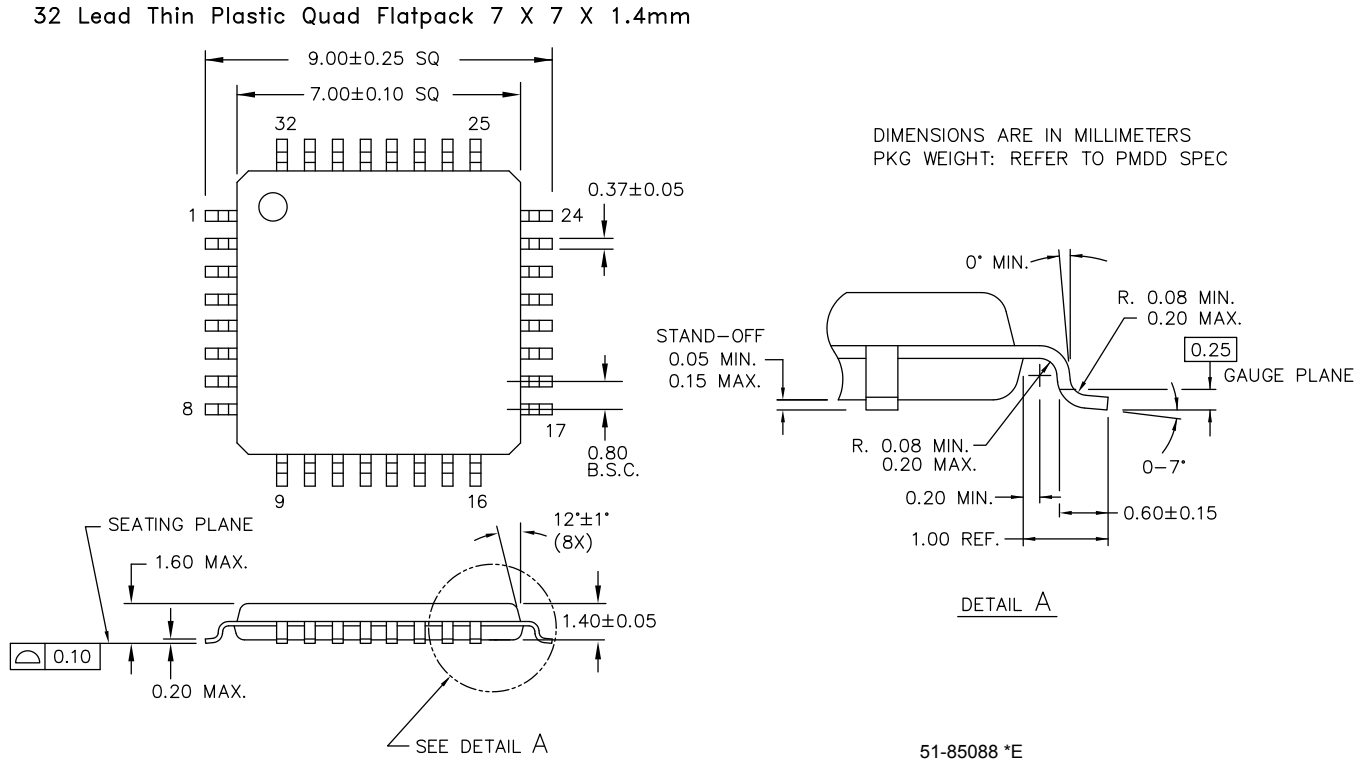
Part Number	Package Type	Production Flow
Pb-free		
CY29940AXI	32-pin TQFP	Industrial, -40 °C to +85 °C
CY29940AXIT	32-pin TQFP – Tape and Reel	Industrial, -40 °C to +85 °C
CY29940AXC	32-pin TQFP	Commercial, 0 °C to 70 °C
CY29940AXCT	32-pin TQFP – Tape and Reel	Commercial, 0 °C to 70 °C

Ordering Code Definitions



Package Drawing and Dimensions

Figure 7. 32-pin TQFP 7 × 7 × 1.4 mm A32.14



Acronyms

Acronym	Description
ESD	electrostatic discharge
I/O	input/output
TQFP	thin quad flat package
LVC MOS	low voltage complementary metal oxide semiconductor
LVPECL	low-voltage positive emitter-coupled logic
LVTTL	low-voltage transistor-transistor logic
TQFP	thin quad flat pack

Document Conventions

Units of Measure

Symbol	Unit of Measure
°C	degree Celsius
kV	kilo Volts
MHz	Mega Hertz
μA	micro Amperes
mA	milli Amperes
mm	milli meter
mV	milli Volts
ns	nano seconds
Ω	ohms
%	percent
pF	pico Farad
ps	pico seconds
V	Volts
W	Watts

Document History Page

Document Title: CY29940, 2.5 V or 3.3 V, 200 MHz, 1:18 Clock Distribution Buffer Document Number: 38-07283				
Rev.	ECN No.	Issue Date	Orig. of Change	Description of Change
**	111094	02/01/02	BRK	New data sheet
*A	116776	08/15/02	HWT	Incorporate results of final characterization using corporate methods, added output impedance on page 3 and added output duty cycle on page 4. Updated Ordering Information : Add commercial temperature range part numbers.
*B	122875	12/21/02	RBI	Add power up requirements to maximum rating information
*C	448379	See ECN	RGL	Add typical value for output-to-output skew Updated Ordering Information : Added Lead-free devices.
*D	2899304	03/25/10	BASH / KVM	Updated Ordering Information : Removed inactive parts. Updated Package Drawing and Dimensions .
*E	3254185	05/11/2011	CXQ	Added Ordering Code Definitions . Added Acronyms and Units of Measure . Updated to new template.
*F	3548252	03/12/2012	PURU	Changed LQFP to TQFP throughout document.
*G	4586288	12/03/2014	PURU	Updated Functional Description : Added "For a complete list of related documentation, click here ." at the end. Updated Package Drawing and Dimensions : Updated Figure 7 (spec 51-85088 – Changed revision from *D to *E).
*H	4787038	06/04/2015	TAVA	Updated to new template. Completing Sunset Review.
*I	5258862	05/04/2016	PSR	Added Thermal Resistance . Updated to new template. Completing Sunset Review.
*J	5973872	11/22/2017	AESATMP8	Updated logo and Copyright.

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